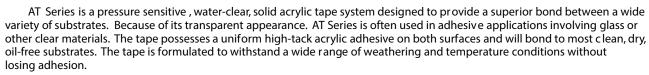
ATSeries Very High Bond Acrylic Tape

PRODUCT DATA SHEET



AT Series can be used in a variety of applications including auto trim attachment, signs, graphics, skin to frame assembly, furniture, appliances, and many other manufacturing and construction applications to replace mechanical fastener and welds.

AT Series offers numerous advantages including a waterproof bond, ease of application, the ability to withstand thermal movement, and sound deadening properties.

ADVANTAGES

- · Pressure sensitive bonding
- · Stain resistant after aged contact
- · Solid composition of easy cutting
- · Moisture resistant
- · Excellent weathering properties
- Reduces and dampens vibration and shock
- · Maintains adhesion at sub-zero temperatures
- · Hardening or brittle resistant with age
- · Fixable, moldable, compressible conforms to intricate shapes

TECHNICAL DATA

Tape Color		Clear
Tape Thickness		0.010, 0.020, 0.025, 0.030, 0.040, and 0.060 in
		0.254, 0.508, 0.635, 03762, 1.016, and 1.524mm
Tape Width		6.35 - 457.2mm
Tensile Strength	ASTM D412 Die C	150 psi
		0.1054 kg/mm2
Elongation	ASTM D412 Die C	1000%
Peel Adhesion	ASTM D3330	10 pli
		1.751 NLMM
Cleavage Peel Strength	ASTM D1062	20 psi
		0.0141 kg/mm2
Dynamic Shear Strength	ASTM D3163	60 psi
		0.0422 kg/mm2
Shelf Life		1 year
Installation Temperature		50°F - 100°F
		10°C - 37.8°C
Constant Temperature Limit		-30°F - 200°F
		-34.4°C - 93.3°C

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ACRYLIC TAPE AND ADHESION PROMOTER APPLICATION GUIDE

PROFESSIONALQUALITY

1. Substrate Evaluation

Acrylic adhesive is suitable for bonding a variety of substrates, including many plastics, composites, sealed wood and metals. Low energy surface materials such as polyethylene, polypropylene, silicone can be a problem bonding. Thorough evaluation is recommended when bonding to any questionable surface. An adhesion promoter (primer) for use with pressure sensitive acrylic adhesives may be necessary to facilitate proper bonding.

2. Preparation of Substrate

The substrate to be bonded should be cleaned with an appropriate solvent, preferably IPA (Isopropanol) no more that 15 minutes prior to bonding of acrylic adhesive backed part. To ensure removal of all contaminants without leaving any residue, use a clean, lint-free wiping cloth or disposable wipe (never recycled rags). Other solvents such as hexane, heptane or methanol may be suitable for cleaning various substrates after thorough evaluation. The substrate must be thoroughly dry through evaporation of the solvent with radiant heat, hot air dryers or with time before bonding acrylic adhesive backed parts. Insure optimum substrate temperature, never below 60°F (15°C) at application time. Assure application temperature of 50°F to 100°F (10°C to 38°C).=

3. Adhesive Promoter Application - If necessary

Apply the AP Series Adhesive Promoter to the substrate(s) either with a lint-free applicator of foam brush. Apply the adhesion Promoter in a "Wet" laydown thickness range of 1-8 mils. Allow the adhesion Promoter to dry approximately (5) Minutes. Don't touch the Adhesion Promoter.

4. Application of Adhesive Backed Part to the Substrate

Remove the protective release liner from the acrylic tape immediately prior to applying the part to be bonded, being careful not to contaminate the acrylic adhesive. Apply within 15 minutes after the adhesion promoter has been applied. Apply the part to be bonded without entrapping air between the tape and the substrate with a recommended application pressure of 15 pounds per inch of tape width to achieve to substrate contact and maximum bond strength.



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